

09/158:6/6

A MULTI-LEVEL ELECTRONIC PACKAGE AND METHOD FOR MAKING SAME

ABSTRACT OF THE DISCLOSURE

A multi-level package, and method for making same, that offers a small size with compartmentalized areas that allow for radiation shielding is disclosed. In its simplest embodiment, the invention comprises two cards and an interposer interposed between the two cards. The interposer preferably has an opening, and the combination of the interposer's opening and the two cards form a cavity. The cavity allows for a high amount of components to be packed into a small, three-dimensional space. The interposer supports can act like a Faraday shield. The two cards and interposer can be multi-layered and support any type of chip or package connection on each side of each card or interposer, including through-hole, surface mount, and direct-chip attachment connections. Finally, pick-up plates or heat sinks can be attached to the package.